

Material Declaration



Package Type	Full
Package Size	20.8 x 13.2 mm
Terminal Finish	Matte Tin
Finish Thickness	8 microns
Weight (mg)	3520.000
MSL	1

Series	CPP
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Item	Material	Element	Content (mg)	Content (wt%)	CAS #	
Cover	Stainless Steel	Nickel (Ni)	65.998	1.875%	7440-02-0	
		Chromium (Cr)	147.164	4.181%	7740-47-3	
		Iron (Fe)	580.860	16.502%	7439-89-6	
		Manganese (Mn)	8.391	0.238%	7439-96-5	
		Silicon (Si)	3.873	0.110%	7440-21-3	
		Carbon (C)	0.355	0.010%	7440-44-0	
		Sulphur (S)	0.008	0.000%	7704-34-9	
		Phosphorus (P)	0.169	0.005%	7723-14-0	
Header	Iron Alloy	Iron (Fe)	2216.313	62.963%	7439-89-6	
		Carbon (C)	1.109	0.032%	7440-44-0	
		Silicon (Si)	0.222	0.006%	7440-21-3	
		Manganese (Mn)	5.113	0.145%	7439-96-5	
		Phosphorus (P)	0.311	0.009%	7723-14-0	
		Sulphur (S)	0.111	0.003%	7704-34-9	
		PTH Glass	Glass Frit	13.514	0.384%	65997-18-4
		Standoff Glass	Glass Frit	47.199	1.341%	65997-18-4
	Kovar	Iron (Fe)	25.465	0.723%	7439-89-6	
		Nickel (Ni)	14.069	0.400%	7440-02-0	
		Cobalt (Co)	8.270	0.235%	7440-48-4	
	Solder Dip	Tin (Sn)	4.866	0.138%	7440-31-5	
		Silver (Ag)	0.151	0.004%	7440-22-4	
		Copper (Cu)	0.025	0.001%	7440-50-8	
	Cover	Kovar	Nickel (Ni)	6.774	0.192%	7440-02-0
Cobalt (Co)			3.943	0.112%	7440-48-4	
Iron (Fe)			12.666	0.360%	7439-89-6	
Alumina (Al2O3)			86.460	2.456%	1344-28-1	
Base	Ceramic	Silicon Dioxide (SiO2)	3.436	0.098%	14808-60-7	
		Chromium Oxide (Cr2O3)	3.690	0.105%	1308-38-9	
		Titanium Oxide (TiO2)	0.958	0.027%	13463-67-7	
		Calcium Oxide (CaO)	0.330	0.009%	1305-79-9	
		Magnesium Oxide (MgO)	0.474	0.013%	1309-48-4	
		Tungsten (W)	13.107	0.372%	7440-33-7	
		Seal Ring	Nickel (Ni)	5.122	0.145%	7440-02-0
			Gold (Au)	0.584	0.017%	7440-57-5
	Iron (Fe)		6.399	0.182%	7439-89-6	
	Silver Solder	Cobalt (Co)	2.434	0.069%	7440-48-4	
		Silver (Ag)	1.872	0.053%	7440-22-4	
		Copper (Cu)	0.330	0.009%	7440-50-8	
		Aluminum (Al)	0.003	0.000%	7429-90-5	
	IC	IC	Titanium (Ti)	0.001	0.000%	7440-32-6
			Silicon (Si)	1.057	0.030%	7440-21-3
Gold (Au)			0.316	0.009%	7440-57-5	
Adhesive			Silver (Ag)	0.00021	0.000%	7440-22-4
Epoxy		0.00007	0.000%			
Capacitor	Body	Nickel (Ni)	0.010	0.000%	7440-02-0	
		BaTiO3	0.830	0.024%	12047-27-7	
		Nickel (Ni)	0.013	0.000%	7440-02-0	
	Termination	Tin (Sn)	0.019	0.001%	7440-31-5	
		Copper (Cu)	0.025	0.001%	7440-50-8	
		Silicon Dioxide (SiO2)	1.123	0.032%	14808-60-7	
Crystal	Electrode	Silver (Ag)	0.021	0.001%	7440-22-4	
		Nickel (Ni)	0.00018	0.000%	7440-02-0	
	Adhesive	Silver (Ag)	0.00041	0.000%	7440-22-4	
		Silicon (Si)	0.00014	0.000%	7440-21-3	
Circuit Board	FR-4	Phenol, 4,4'-(1-methylethylidene)bis(2,6-dibromo-polymer with (chloromethyl)oxirane and 4,4'-(1-methylethylidene)bis(phenoxy))	72.19096457	2.051%	26265-08-7	
		Copper (Cu)	39.37688977	1.119%	7440-50-8	
		GF-Fibre	107.1926444	3.045%		
		Copper Anode	Copper (Cu)	3.65626161	0.104%	7440-50-8
	Soldermask	Bisphenol A, epichlorohydrin polymer	0.608170839	0.017%	25068-38-6	
		2-Methoxymethylethoxy)phenol	0.15204271	0.004%	34590-94-8	
		Barium sulphate	0.532149484	0.015%	7727-43-7	
		2-Methyl-1-(4-methylthiophenyl)-2-morpholinopropan-1-one	0.15204271	0.004%	71868-10-5	
		Dipropylene glycol ethyl ether	0.076021355	0.002%	15764-24-6	
	ENIG	Nickel bis(sulphamate)	0.491604761	0.014%	13770-89-3	
		Gold (Au)	0.015204271	0.000%	7440-57-5	
	Total			3520.000	100.000%	



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